

METAL FOIL CHIP FIXED RESISTOR

- CML SERIES -

FEATURES

- The highest power is up to 2W
- The lowest TCR is 50 ppm/°C
- Current detecting resistors for power supply, etc
- Superior mechanical and frequency characteristics
- Compliant with RoHS directive
- Halogen free requirement



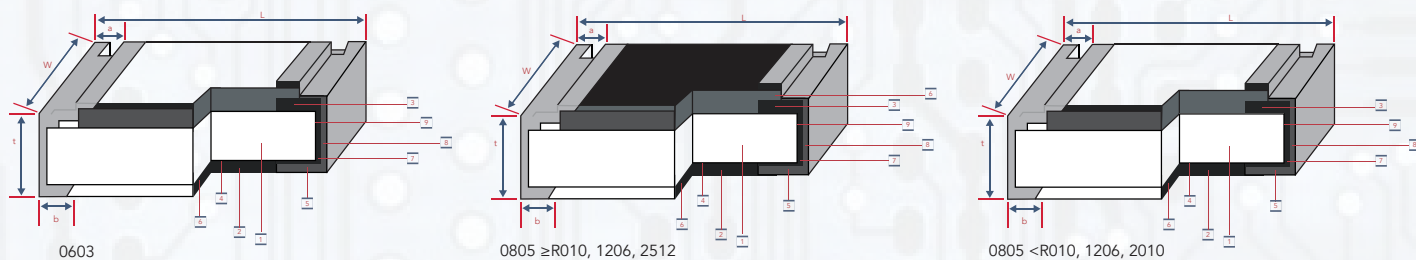
APPLICATIONS

- Switching Power Supply, Over Current Protection, Voltage Regulation Module (VRM), DC-DC Converter, Charger, Portable Devices, etc.

TYPE DESIGNATION

CM	L	6432	C	R010	F	T
PRODUCT CODE	POWER RATING SERIES CODE	TYPE CODE	TCR CODE	RESISTANCE VALUE CODE	RESISTANCE TOLERANCE CODE	PACKAGING STYLE CODE
Metal Foil Chip Fixed Resistor	G - 1/2W H - 3/4 W J - 1W L - 2W	1608 - 0603 2012 - 0805 3216 - 1206 5025 - 2010 6432 - 2512	C - ±50 K - ±100 W - ±200	Units: Ω Decimal point should be expressed by 'R' Units: Ω Decimal point should be expressed by 'M' R005 - 0.005Ω R100 - 0.100Ω R047 - 0.047Ω 6M50 - 6.50MΩ	F - ±1% G - ±2% J - ±5%	T - Tap & Reel C - Case

CONSTRUCTION

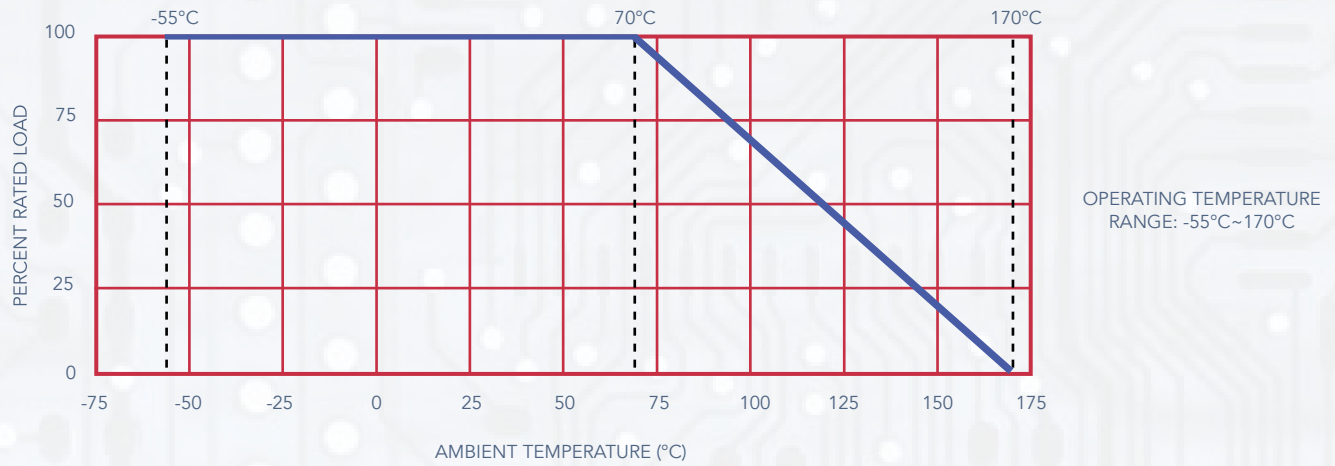


- 1 Ceramic Substrate
- 2 Alloy Plate
- 3 Top Electrode
- 4 Primary Overcoat
- 5 Barrier Layer (Ni)
- 6 External Electrode (Sn)
- 7 Edge Electrode
- 8 Barrier Layer
- 9 External Electrode

DIMENSIONS

TYPE	M Ω	L (MM)	W (MM)	t (MM)	a (MM)	b (MM)
0603	≥R005	1.6±0.20	0.80±0.20	0.70±0.15	0.35±0.25	0.35±0.20
0805	R003-R004	2.00±0.20	1.25±0.20	0.70±0.15	0.40±0.25	0.70±0.30
	≥R005					0.40±0.30
1206	R003-R004	3.20±0.20	1.60±0.20	0.75±0.15	0.50±0.30	0.90±0.30
	≥R005					0.50±0.30
2010	R003	5.00±0.20	2.50±0.20	0.75±0.20	0.60±0.30	1.60±0.30
	R004-R005					1.30±0.30
	>R005					0.80±0.30
	R002					2.30±0.30
2512	R003	6.40±0.20	3.20±0.20	0.75±0.20	0.90±0.30	1.90±0.30
	R004					1.70±0.30
	R005-R006					1.20±0.30
	R007					1.10±0.30
	>R007					0.90±0.30

DERATIVE CURVE



NOTE: For resistors operated in ambient over 70°C, rated load (rated power) shall be derated in accordance with the above figure.

RATINGS

TYPE	RATING POWER AT 70°C (W)	LIMITING ELEMENT CURRENT (A)	MAX. OVERLOAD CURRENT (A)	RESISTANCE RANGE CURRENT (A)
0603	1/2	10	22.4	$0.005\Omega \leq R \leq 0.030\Omega$
0805	1/2, 3/4	15.8	35.4	$0.003\Omega \leq R \leq 0.047\Omega$
1206	1/2, 1	18.3	40.8	$0.003\Omega \leq R \leq 0.068\Omega$
2010	1	18.3	40.8	$0.003\Omega \leq R \leq 0.100\Omega$
2512	2	31.6	63.3	$0.003\Omega \leq R \leq 0.100\Omega$
	1	3.20	7.10	$0.003\Omega \leq R \leq 0.200\Omega$

NOTE:
 1. Current of DC or AC RMS Value
 2. $I = \sqrt{P/R}$ or Limiting element current whichever is lower
 I - Rated current (A)
 P - Rated power (W)
 R - Normal resistance (Ω)

TYPE	RESISTANCE RANGE	T.C.R. (PPM/°C)		
		RESISTANCE TOLERANCE		
		±1%	±2%	±5%
0603	$0.005\Omega \leq R \leq 0.010\Omega$	±200	±200	±200
	$0.010\Omega \leq R \leq 0.030\Omega$	±100	±100	±100
0805	$0.003\Omega \leq R \leq 0.010\Omega$	±100	±100	±100
	$0.010\Omega \leq R \leq 0.047\Omega$	±50	±50	±50
1206	$0.003\Omega \leq R \leq 0.010\Omega$	±100	±100	±100
	$0.010\Omega \leq R \leq 0.068\Omega$	±50	±50	±50
2010	$0.003\Omega \leq R \leq 0.010\Omega$	±100	±100	±100
	$0.010\Omega \leq R \leq 0.100\Omega$	±50	±50	±50
2512	0.002 Ω	±200	±200	±200
	$0.003\Omega \leq R \leq 0.010\Omega$	±100	±100	±100
	$0.010\Omega \leq R \leq 0.200\Omega$	±50	±50	±50

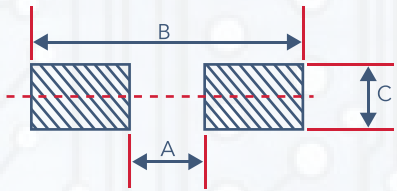
NOTE: The chip resistor with resistance value below 0.010 Ω and TCR ± 50 ppm/°C can be customized



CHARACTERISTICS

ITEM	SPECIFICATIONS	TEST METHODS (IEC60115-1)
SOLDERABILITY	95% Cover Min	IEC 60115-1 4.17 Lead-free solder bath at 245°C ± 5°C for 3s±0.3s
RESISTANCE TO SOLDERING HEAT	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.18 Lead-free solder bath at 270°C ± 5°C for 10s±1s
SUBSTRATE BENDING TEST	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.33 Bending distance: 0603, 0805, 1206, 3mm; 2010, 2512: 2mm Duration: 60s ± 5s.
T.C.R.	Within specified T.C.R.	IEC 60115-1 4.8 +20°C/+125°C/+20°C
RAPID CHANGE OF TEMPERATURE	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.19 -55°C (30 min) ~ normal temperature (5 min) ~ 125°C (30 min) 100 cycles
SHORT TIME OVERLOAD	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.13 1/2W, 3/4W, 1W: 5 X Rated Power, for 5s. 2W: 4 X Rated Power, for 5 s.
DAMP HEAT STEADY STATE	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.24 40°C ±2°C, 93% ± 3% RH, 1000h, rated current or limiting element current whichever is lower for 1.5h ON/0.5h OFF.
ENDURANCE AT 70°C	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.25.1 70°C ±2°C, 1000h, rated current or limiting element current whichever is lower for 1.5h ON/0.5h OFF.
ENDURANCE AT UPPER CATEGORY TEMPERATURE	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.25.3 +170°C ±2°C, 1000h
INSULATION RESISTANCE	1000M Ω Min	IEC 60115-1 4.6 Apply DC 100V ± 15V between substrate and terminations for 1min, then check insulation resistance
VOLTAGE PROOF	No breakdown or flashover	IEC 60115-1 4.7 Apply max. overload voltage of AC RMS at a rate of approximately 100V/s between substrate and terminations for 60s±5s
COMPONENT SOLVENT RESISTANCE	No mechanical damage ΔR _s ±1.0%	IEC 60115-1 4.29 Iso-propyl alcohol (IPA), 23°C ±5°C, 10h

RECOMMEND SOLDER PAD SIZE



TYPE	m Ω	A	B	C
0603	R005~R030	0.6	2.8	1.0
0805	R003~R004	0.5	3.2	1.4
	R005~R047	0.8		
1206	R003~R004	0.8	4.4	1.8
	R005~R068	1.8		
2010	R003~R009	1.6	6.3	2.9
	R010~R100	2.7		
2512	R002~R004	1.0	8.0	3.4
	R005~R200	3.8		